

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

18.03.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
---------------	----------	----	---------	------------------

A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	238		2		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3		
		18	L2			
C-RS-FR4-ML-0.610mm-018+018-TG150-HF-...	50203032	610		4	A00	B00
		18	L3			
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	238		5		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6		
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	7		

Thickness after Pressing

B00:

1090 µm

Tol+:

120 µm

Tol-:

120 µm

Dmax:

1210 µm

Dmin:

970 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1200 µm

Tol+:

120 µm

Tol-:

120 µm

Dmax:

1320 µm

Dmin:

1080 µm

Measuring point:

(05) over SM and galv. Cu; both sides

nominal:

1158 µm

Version 1.2.20.35

© Würth Elektronik